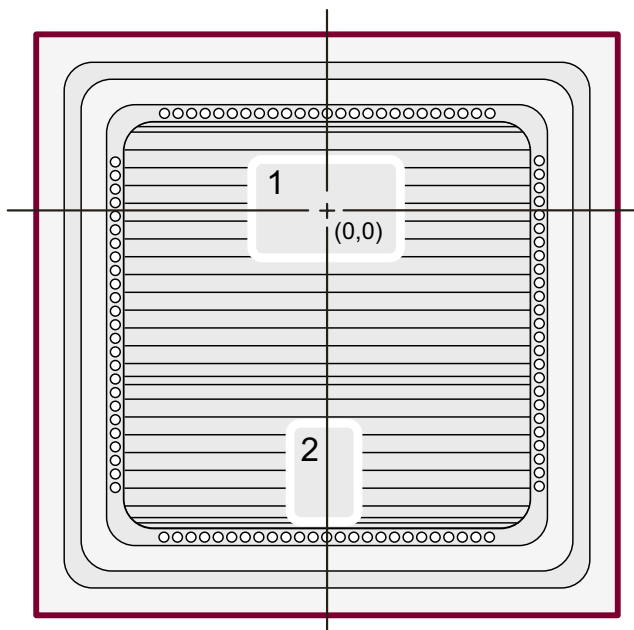


**Pad Layout**



**Backside: Drain**

**Die Specifications**

Device	Die Dimensions			Back Side Metal	Back Side	Bonding Pad Material
	Length <sup>1</sup> (mils)	Width <sup>1</sup> (mils)	Thickness (mils)			
TN0104	37	37	11 ± 1.5	Au	Drain	Al/Cu/Si

**Bonding Pad Description**

Pad #	Function	x Position <sup>2</sup> (mils)	y Position <sup>2</sup> (mils)	x Size (mils)	y Size (mils)
1	Source	0	0	9.0	6.3
2	Gate	0	-17.1	4.3	5.1

**Notes:**

1. Maximum values.
2. Position referenced to center of pad.

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